

PATENT 0152-0551P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:

ARIYASU, Hideyuki et al. Conf.:

7701

Appl. No.:

09/773,627

Group:

1773

Filed:

February 2, 2001

Examiner: KRUER, Kevin

For:

THERMOPLASTIC RESIN INTEGRATED

STRUCTURE

## LARGE ENTITY TRANSMITTAL FORM

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

October 19, 2004

Sir:

Transmitted herewith is an amendment in the above-identified application.

- The enclosed document is being transmitted via the Certificate of Mailing provisions of 37 C.F.R. § 1.8.
- The enclosed document is being transmitted via facsimile.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR		PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	53	-	60	=	0	\$ 18	\$0.00
INDEPENDENT	2	-	3	=	0	\$ 88	\$0.00
FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM							\$0.00
						TOTAL	\$0.00

		(s) extension of time pursuant to $S(a)$ . \$0.00 for the extension of				
$\boxtimes$	No fee is required.					
	Check(s) in the amount of \$0.00 is(are) enclosed.					
	Please charge Deposit Account No. 02-2448 in the amount of \$0.00. This form is submitted in triplicate.					
overprequ:	current, and future replies, rpayment to Deposit Account No	ner is hereby authorized in this, to charge payment or credit any o. 02-2448 for any additional fees 16 or under 37 C.F.R. § 1.17; fees.				
	Resp	pectfully submitted,				
	BIRO	CH, STEWART, KOLASCH & BIRCH, LLP				
	ву <u></u> <u>{</u> <u>В</u>	aymord C. Stewart, #21,066				
	/RG/jmb Fall	Box 747  S Church, VA 22040-0747  3) 205-8000				

Attachment(s)



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THERMOPLASTIC RESIN INTEGRATED STRUCTURE

## REQUEST FOR RECONSIDERATION

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 October 19, 2004

Sir:

Responsive to the Office Action of July 29, 2004, the following amendments and Remarks are respectfully submitted in connection with the above-identified application.

This response includes:

Remarks; and

Claims Appendix.